

02/22/02

Docket No. 5853-223

PATENT APPLICATION TRANSMITTAL LETTER

Commissioner for Patents
BOX PATENT APPLICATION
 Washington, DC 20231

J1050 U.S. PTO
 10/08/1979
 02/22/02

Transmitted herewith for filing of the patent application of:

Inventor(s): Rajiv K. Singh
 Seung-Mahn Lee

for **IMPROVED CHEMICAL-MECHANICAL POLISHING SLURRY FOR POLISHING OF COPPER OR SILVER FILMS**

are the following:

- Specification, including Abstract
- 16 Sheets of drawing (3 sets)
- X Executed Declaration and Power of Attorney
- X Assignment with Recordation Cover Sheet
- X Other: 2 postcards

CLAIMS AS FILED

FOR	NO. FILED	NO. EXTRA
Basic Fee		
Total Claims	45	25
Indep Claims	8	5
multiple dependent claim present		No

If the difference in Col. 1 is less than zero, enter "0" in Col. 2
 Assignment Recordation

Small Entity

RATE	FEES
	\$370.00
x \$ 9 =	\$ 225.00
x \$ 42 =	\$ 210.00
x \$135 =	\$
TOTAL	\$ 805.00
	\$ 40.00

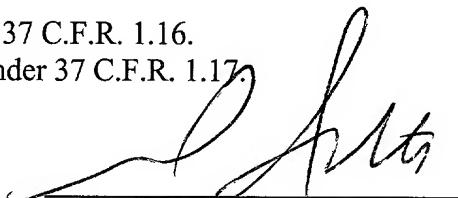
Other than a Small Entity

RATE	FEES
	\$ 740.00
x \$ 18 =	\$
x \$ 84 =	\$
x \$270 =	\$
TOTAL	\$

- X You are hereby authorized to charge \$845.00 to Deposit Account No. 50-0951.
- X The Commissioner is hereby authorized to charge any underpayment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-0951.
- A duplicate of this sheet is enclosed.
- X Any additional filing fees required under 37 C.F.R. 1.16.
- X Any patent application processing fees under 37 C.F.R. 1.17.

Date

02/22/02



Neil R. Jetter
 Registration No. 46,803